

PCN Number:	20221017001.1		PCN Date:	December 02, 2022																			
Title:	Transfer of select C10 devices from ANAM-1 to DMOS5 Wafer Fab site																						
Customer Contact:	PCN Manager		Dept:	Quality Services																			
Proposed 1st Ship Date:	Jan 17, 2023		Sample requests accepted until:	Nov 17, 2022*																			
*Sample requests received after November 17, 2022 will not be supported.																							
Change Type:																							
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials																		
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification																		
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process																		
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process																		
<input checked="" type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process																		
		<input type="checkbox"/>	Part number change																				
PCN Details																							
Description of Change:																							
<p>Revision A is to announce the <u>addition</u> of eight new devices that were not included in the original PCN notification. The new devices are highlighted in yellow and bolded in the product affected section below. For these newly added devices ONLY, the expected first shipment date for the new devices will be 90 days from the date of this notice, and sample requests will be accepted until 30 days from the date of this notice. The proposed 1st ship date of January 17, 2023 still applies for the original set of devices.</p>																							
<p>This change notification is to announce the transfer of select devices from ANAM-1 to the DMOS5 Wafer Fab site. Fab support from ANAM-1 has been discontinued. Buffer inventory has been built to cover the notification period of this change notification.</p>																							
<table border="1"> <thead> <tr> <th colspan="3">Current (Discontinued)</th> <th colspan="3">New (Transfer to Location)</th> </tr> <tr> <th>Current Fab Site</th> <th>Fab Process</th> <th>Wafer Diameter</th> <th>New Fab Site</th> <th>Fab Process</th> <th>Wafer Diameter</th> </tr> </thead> <tbody> <tr> <td>ANAM-1</td> <td>C10</td> <td>200mm</td> <td>DMOS5</td> <td>C10</td> <td>200mm</td> </tr> </tbody> </table>						Current (Discontinued)			New (Transfer to Location)			Current Fab Site	Fab Process	Wafer Diameter	New Fab Site	Fab Process	Wafer Diameter	ANAM-1	C10	200mm	DMOS5	C10	200mm
Current (Discontinued)			New (Transfer to Location)																				
Current Fab Site	Fab Process	Wafer Diameter	New Fab Site	Fab Process	Wafer Diameter																		
ANAM-1	C10	200mm	DMOS5	C10	200mm																		
Qual details are provided in the Qual Data Section.																							
Reason for Change:																							
Discontinued Fab support from ANAM-1																							
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):																							
None																							
Changes to product identification resulting from this PCN:																							
Current																							
Chip Site	Chip Site Origin (20L)	Chip Site Country Code (21L)	Chip Site City																				
ANAM-1	ANM	KOR	Bucheon-si																				
New Fab Site																							
Chip Site	Chip Site Origin (20L)	Chip Site Country Code (21L)	Chip Site City																				
DP1DM5	DM5	USA	Dallas																				

Sample product shipping label (not actual product label)



MADE IN: Malaysia
2DC: 20:



MSL 2 / 260C / 1 YEAR	SEAL DT
MSL 1 / 235C / UNLIM	03/29/04

OPT:
ITEM: 39
LBL: 5A (L) TO: 1750

(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY (1T) 7523483S12
(P)
(2P) REV: (V) 0033317
(20L) CS0: SHE (21L) CCO: USA
(22L) AS0: MLA (23L) ACO: MYS

Product Affected Group:

CDCLVD1208RHDR	CDCLVD1213RGTR	CDCLVD2102RGTR	CDCLVD2106RHAR
CDCLVD1208RHDT	CDCLVD1213RGTT	CDCLVD2102RGTT	CDCLVD2106RHAT
CDCLVD1212RHAR	CDCLVD1216RGZR	CDCLVD2104RHDR	
CDCLVD1212RHAT	CDCLVD1216RGZT	CDCLVD2104RHDT	

Qualification Report
Approve Date 1-August-2022

Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: CDCLVD1212RHAR	Qual Device: CDCLVD1216RGZR	Qual Device: CDCLVD2106RHAR	QBS Reference: TLK2500IRCP	QBS Reference: TLK2201BIRCP
AC	Autoclave 121C, 2atm	96 Hours	-	-	-	3/231/0	3/231/0
CDM	ESD - CDM	1500 V	-	-	-	-	1/3/0
ED	Electrical Characterization	Per Data Sheet Parameters	-	-	-	Pass	Pass
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	3/231/0	-
HBM	ESD - HBM	4000 V	-	-	-	-	1/3/0
HTOL	Life Test, 155C	240 Hours	-	-	-	3/231/0	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	-	-	3/135/0	3/135/0
LU	Latch-up	(Per JESD78)	-	-	-	-	1/6/0
T/C	Temp Cycle -65C/150C	500 Cycles	-	-	-	-	3/231/0
WBP	Bond Pull	Wires	Pass	Pass	Pass	-	-
WPS	Ball Bond Shear	Wires	Pass	Pass	Pass	-	-

- Qual Devices qualified at LEVEL3-260C: CDCLVD1212RHAR, CDCLVD1216RGZR, CDCLVD2106RHAR
 - QBS: Qual By Similarity
 - Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
 - The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
 - The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
 - The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
 Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:
Qualified Pb-Free(SMT) and Green

Qualification Report

Approve Date 22-November-2022

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: CDCLVD1208RHDR	Qual Device: CDCLVD1213RGTR	Qual Device: CDCLVD2102RGTR	Qual Device: CDCLVD2104RHDR	QBS Reference: TLK2500IRCP	QBS Reference: TLK2201BIRCP
AC	Autoclave 121C, 2atm	96 Hours	-	-	-	-	3/231/0	3/231/0
CDM	ESD - CDM	1500 V	-	-	-	-	-	1/3/0
ED	Electrical Characterization	Per Data Sheet Parameters	-	-	-	-	Pass	Pass
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	-	3/231/0	-
HBM	ESD - HBM	4000 V	-	-	-	-	-	1/3/0
HTOL	Life Test, 155C	240 Hours	-	-	-	-	3/231/0	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	-	-	-	3/135/0	3/135/0
LU	Latch-up	(Per JESD78)	-	-	-	-	-	1/6/0
T/C	Temp Cycle - 65C/150C	500 Cycles	-	-	-	-	-	3/231/0
WBP	Bond Pull	Wires	Pass	Pass	Pass	Pass	-	-
WPS	Ball Bond Shear	Wires	Pass	Pass	Pass	Pass	-	-

- Qual Devices qualified at LEVEL2-260C: Qual Device: CDCLVD1208RHDR, CDCLVD1213RGTR, CDCLVD2102RGTR, CDCLVD2104RHDR

- QBS: Qual By Similarity

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

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Location	E-Mail
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